

CAT661

High Frequency 100mA CMOS Charge Pump, Inverter/Doubler



FEATURES

- Converts V+ to V- or V+ to 2V+
- Low output resistance, 10Ω max.
- High power efficiency
- Selectable charge pump frequency of 25kHz or 135kHz; optimize capacitor size.
- Low quiescent current

- Pin-compatible to MAX660, LTC660 with higher frequency operation
- Available in 8-pin SOIC, DIP and 0.8mm thin 4x4mm TDFN packages
- Lead-free, halogen-free package option

APPLICATIONS

- Negative voltage generator
- Voltage doubler
- Voltage splitter

- Low EMI power source
- GaAs FET biasing
- Lithium battery power supply
- Instrumentation
- LCD contrast bias
- **■** Cellular phones, pagers

DESCRIPTION

The CAT661 is a charge-pump voltage converter. It can invert a positive input voltage to a negative output. Only two external capacitors are needed. With a guaranteed 100mA output current capability, the CAT661 can replace a switching regulator and its inductor. Lower EMI is achieved due to the absence of an inductor.

In addition, the CAT661 can double a voltage supplied from a battery or power supply. Inputs from 2.5V to 5.5V will yield a doubled, 5V to 11V output.

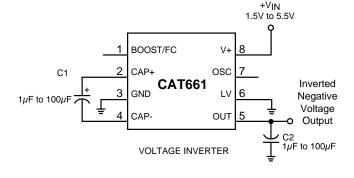
A Frequency Control pin (BOOST/FC) is provided to select either a high (typically 135kHz) or low (25kHz) internal oscillator frequency, thus allowing quiescent current vs. capacitor size trade-offs to be made. The 135kHz frequency is selected when the FC pin is

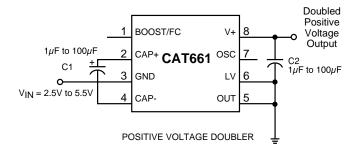
connected to V+. The operating frequency can also be adjusted with an external capacitor at the OSC pin or by driving OSC with an external clock.

Both 8-pin DIP and SO packages are available. The TDFN package 4x4mm footprint features a 0.8mm maximum height. For die availability, contact Catalyst Semiconductor marketing.

The CAT661 can replace the MAX660 and the LTC660 in applications where higher oscillator frequency and smaller capacitors are needed. In addition, the CAT661 is pin compatible with the 7660/1044, offering an easy upgrade for applications with 100mA loads.

TYPICAL APPLICATION





PIN CONFIGURATION

SO Package (S, X)

DIP Package (P)

TDFN Package (RD8, ZD8)

		T)		
BOOST/FC	17		8	V+
CAP+	2	CAT661	<u>.</u> 7_	osc
GND	3_	! !	6	LV
CAP-	4_	ii	5_	OUT

(Top View)
TDFN Package: 4mm x 4mm
0.8mm maximum height

PIN DESCRIPTIONS

		Circuit Configuration		
Pin Number	Name	Inverter		Doubler
1	Boost/FC	Frequency Control for the internal oscillator. With an external oscillator BOOST/FC has no effect.		Same as inverter.
		Boost/FC	Oscillator Frequency	
		Open	25kHz typical, 10kHz minimum	
		V+	135kHz typical, 80kHz minimum	
2	CAP+	Charge Pur	np Capacitor. Positive terminal.	Same as inverter.
3	GND	Power Supp	oly Ground.	Power supply. Positive voltage input.
4	CAP-	Charge pun	np capacitor. Negative terminal.	Same as inverter.
5	OUT	Output for negative voltage.		Power supply ground.
6	LV	voltage is le For input vo connected to	e selection pin. When the input ss than 3V, connect LV to GND. oltages above 3V, LV may be to GND or left open. If OSC is nally, connect LV to GND.	LV must be tied to OUT for all input voltages.
7	osc	Oscillator control input. An external capacitor can be connected to lower the oscillator frequency. An external oscillator can drive OSC and set the chip operating frequency. The charge-pump frequency is one-half the frequency at OSC.		Same as inverter. Do not overdrive OSC in doubling mode. Standard logic levels will not be suitable. See the applications section for additional information.
8	V+	Power supp	ly. Positive voltage input.	Positive voltage output.

ORDERING INFORMATION

Part Number	Package	Temperature Range
CAT661EPA	8 lead Plastic DIP	-40°C to 85°C
CAT661ESA	8-lead SO	-40°C to 85°C
CAT661ESA-TE13	8-lead SO, Tape & Reel	-40°C to 85°C
CAT661EVA	8-lead SO (Lead-free, Halogen-free)	-40°C to 85°C
CAT661EVA-TE13	8-lead SO (Lead-free, Halogen-free)	-40°C to 85°C
CAT661ERD8	8-pad TDFN	-40°C to 85°C
CAT661EZD8	8-pad TDFN (Lead-free, Halogen-free)	-40°C to 85°C

ABSOLUTE MAXIMUM RATINGS

V+ to GND	6V
Input Voltage (Pins 1, 6 and 7)0.3V to (V+	- + 0.3V)
BOOST/FC and OSC Input Voltage T negative of (Out - 0.3V) or (V+ - 6V) to (V+ +	
Output Short-circuit Duration to GND	1 sec.
(OUT may be shorted to GND for 1 sec without damage shorting OUT to V+ should be avoided.)	e but
Continuous Power Dissipation (T _A = 70°C)	
Plastic DIP	. 730mW
SO	.500mW
TDFN	1W

Storage Temperature	65°C to 160°C
Lead Soldering Temperature (10	sec) 300°C
ESD Rating-Human Body Model	2000V
Lead Soldering Temperature (10	sec) 300°C

Note: T_A = Ambient Temperature

These are stress ratings only and functional operation is not implied. Exposure to absolute maximum ratings for prolongued time periods may affect device reliability. All voltages are with respect to ground.

Operating Ambient Temperature Ranges

CAT661E -40°C to 85°C

ELECTRICAL CHARACTERISTICS

V+ = 5V, C1 = C2 = 100μ F, Boost/FC = Open, C_{OSC} = 0pF, and Test Circuit is Figure 1 unless otherwise noted. Temperature is $T_A = T_{AMIN}$ to T_{AMAX} unless otherwise noted.

Parameter	Symbol	Conditions	Min.	Тур	Max.	Units
		Inverter: LV = Open. $R_L = 1k\Omega$	3.0		5.5	V
Supply Voltage	VS	Inverter: LV = GND. $R_L = 1k\Omega$	1.5		5.5	
		Doubler: LV = OUT. $R_L = 1k\Omega$	2.5		5.5	
Supply Current	IS	BOOST/FC = open, LV = Open		0.2	0.5	mA
		BOOST/FC = V+ , LV = Open		1	3	
Output Current	IOUT	OUT is more negative than -4V	100			mA
Output Resistance	RO	C1 = C2 = 10μF,		3.5	10	Ω
		BOOST/FC = V+ (C1, C2 ESR \leq 0.5 Ω)				
		C1 = C2 = 100μF (Note 2)		3.5	10	
Oscillator Frequency	FOSC	BOOST/FC = Open	10	25		kHz
(Note 3)		BOOST/FC = V+	80	135		
OSC Input Current	IOSC	BOOST/FC = Open		±2		μΑ
		BOOST/FC = V+		±10		
Power Efficiency	PE	$R_L = 1k\Omega$ connected between V+ and	96	98		%
		OUT, $T_A = 25^{\circ}C$ (Doubler)				
		$R_L = 500\Omega$ connected between GND and	92	96		
		OUT, T _A = 25°C (Inverter)				
		$I_L = 100$ mA to GND, $T_A = 25$ °C (Inverter)		88		
Voltage Conversion	VEFF	No load, T _A = 25°C	99	99.9		%
Efficiency						

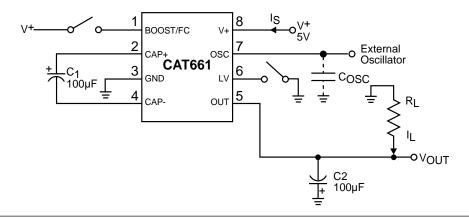
^{1.} In Figure 1, test circuit electrolytic capacitors C1 and C2 are $100\mu F$ and have 0.2Ω maximum ESR. Higher ESR levels may reduce efficiency and output voltage.

3

^{2.} The output resistance is a combination of the internal switch resistance and the external capacitor ESR. For maximum voltage and efficiency keep external capacitor ESR under 0.2Ω .

^{3.} FOSC is tested with C_{OSC} = 100pF to minimize test fixture loading. The test is correlated back to C_{OSC} =0pF to simulate the capacitance at OSC when the device is inserted into a test socket without an external C_{OSC} .

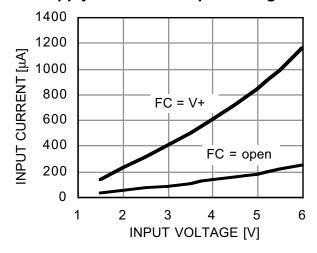
Figure 1. Test Circuit Voltage Inverter



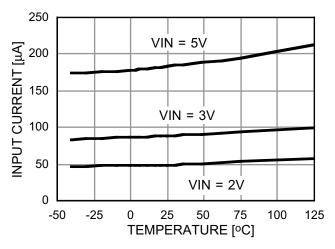
TYPICAL OPERATING CHARACTERISTICS

Typical characteristic curves are generated using the circuit in Figure 1. Inverter test conditions are: V+5V, LV=GND, BOOST/FC=Open and $T_A=25^{\circ}C$ unless otherwise indicated. Note that the charge-pump frequency is one-half the oscillator frequency.

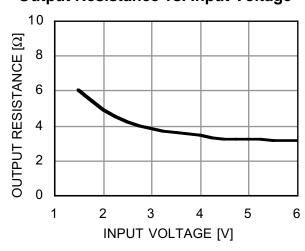
Supply Current vs. Input Voltage



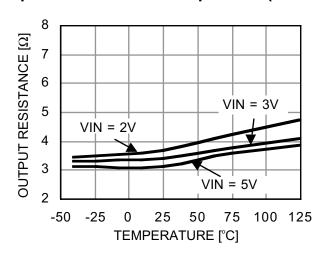
Supply Current vs. Temperature (No Load)



Output Resistance vs. Input Voltage

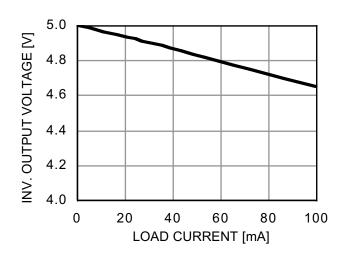


Output Resistance vs. Temperature (50 Ω load)

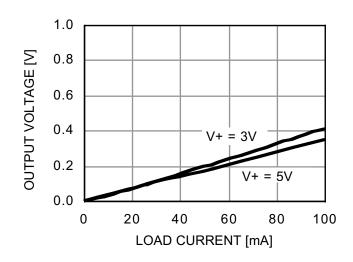


TYPICAL OPERATING CHARACTERISTICS

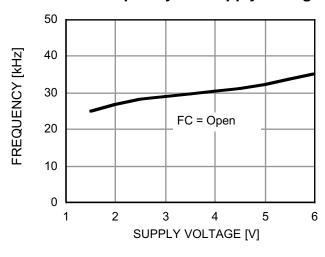
Inverted Output voltage vs. Load, V+ = 5V



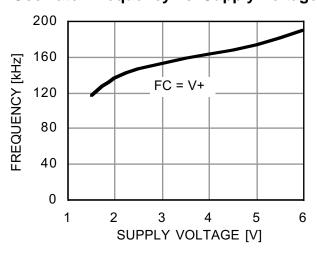
Output Voltage Drop vs. Load Current



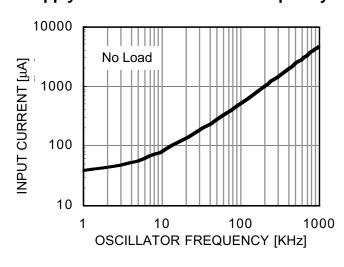
Oscillator Frequency vs. Supply Voltage



Oscillator Frequency vs. Supply Voltage



Supply Current vs. Oscillator Frequency



Efficiency vs. Load Current

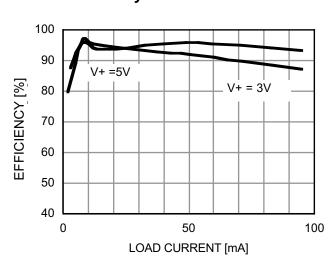
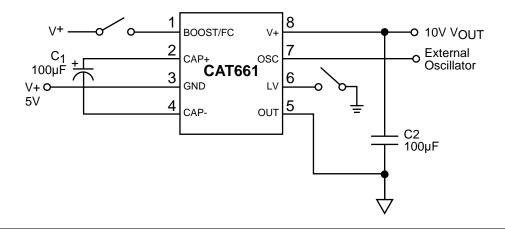


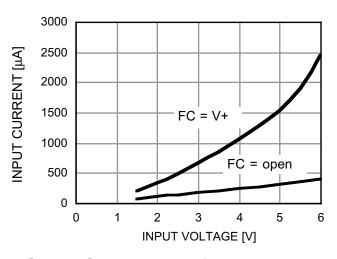
Figure 2. Test Circuit Voltage Doubler



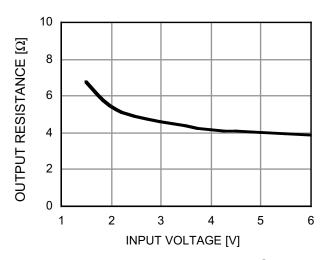
TYPICAL OPERATING CHARACTERISTICS

Typical characteristic curves are generated using the circuit in Figure 2. Doubler test conditions are: V+5V, LV=GND, BOOST/FC=Open and $T_A=25^{\circ}C$ unless otherwise indicated.

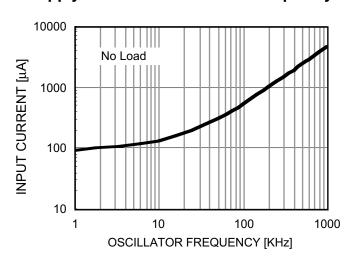
Supply Current vs. Input Voltage (No Load)



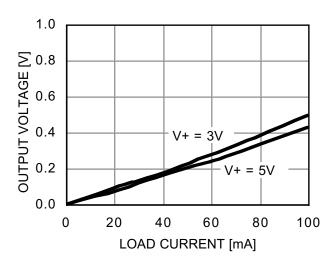
Output Resistance vs. Input Voltage



Supply Current vs. Oscillator Frequency



Output Voltage Drop vs. Load Current



APPLICATION INFORMATION

Circuit Description and Operating Theory

The CAT661 switches capacitors to invert or double an input voltage.

Figure 3 shows a simple switch capacitor circuit. In position 1 capacitor C1 is charged to voltage V1. The total charge on C1 is Q1 = C1V1. When the switch moves to position 2, the input capacitor C1 is discharged to voltage V2. After discharge, the charge on C1 is Q2 = C1V2.

The charge transferred is:

$$\Delta Q = Q1 - Q2 = C1 \times (V1 - V2)$$

If the switch is cycled "F" times per second, the current (charge transfer per unit time) is:

$$I = F \times \Delta Q = F \times C1 \text{ (V1 - V2)}$$

Rearranging in terms of impedance:

$$I = \frac{(V1-V2)}{(1/FC1)} = \frac{V1-V2}{REQ}$$

The 1/FC1 term can be modeled as an equivalent impedance REQ. A simple equivalent circuit is shown in figure 4. This circuit does not include the switch resistance nor does it include output voltage ripple. It does allow one to understand the switch-capacitor topology and make prudent engineering tradeoffs.

For example, power conversion efficiency is set by the output impedance, which consists of REQ and switch resistance. As switching frequency is decreased, REQ, the 1/FC1 term, will dominate the output impedance, causing higher voltage losses and decreased efficiency. As the frequency is increased quiescent current increases. At high frequency this current becomes significant and the power efficiency degrades.

The oscillator is designed to operate where voltage losses are a minimum. With external $150\mu F$ capacitors, the internal switch resistances and the Equivalent Series Resistance (ESR) of the external capacitors determine the effective output impedance.

A block diagram of the CAT661 is shown in figure 5.

Figure 3. Switched-Capacitor Building Block

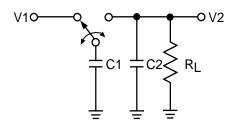
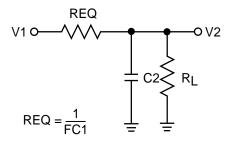


Figure 4. Switched-Capacitor Equivalent Circuit



OSCILLATOR FREQUENCY CONTROL

The switching frequency can be raised, lowered or driven from an external source. Figure 6 shows a functional diagram of the oscillator circuit.

The CAT661 oscillator has four control modes:

BOOST/FC Pin Connection	OSC Pin Connection	Nominal Oscillator Frequency
Open	Open	25kHz
BOOST/FC= V+	Open	135kHz
Open or BOOST/FC= V+	External Capacitor	_
Open	External Clock	Frequency of external clock

If BOOST/FC and OSC are left floating (Open), the nominal oscillator frequency is 25kHz. The pump frequency is one-half the oscillator frequency.

By connecting the BOOST/FC pin to V+, the charge and discharge currents are increased, and the frequency is increased by approximately 6 times. Increasing the frequency will decrease the output impedance and ripple currents. This can be an advantage at high load currents. Increasing the frequency raises quiescent current but allows smaller capacitance values for C1 and C2.

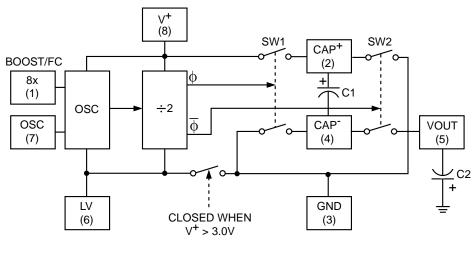
If pin 7, OSC, is loaded with an external capacitor the frequency is lowered. By using the BOOST/FC pin and

an external capacitor at OSC, the operating frequency can be set.

Note that the frequency appearing at CAP+ or CAP- is one-half that of the oscillator.

Driving the CAT661 from an external frequency source can be easily achieved by driving Pin 7 and leaving the BOOST pin open, as shown in figure 6. The output current from Pin 7 is small, typically 1 μA to 8 μA , so a CMOS can drive the OSC pin. For 5V applications, a TTL logic gate can be used if an external 100k Ω pull-up resistor is used as shown in figure 7.

Figure 5. CAT661 Block Diagram



(N) = Pin Number

CAPACITOR SELECTION

Low ESR capacitors are necessary to minimize voltage losses, especially at high load currents. The exact values of C1 and C2 are not critical but low ESR capacitors are necessary.

The ESR of capacitor C1, the pump capacitor, can have a pronounced effect on the output. C1 currents are approximately twice the output current and losses occur on both the charge and discharge cycle. The ESR effects are thus multiplied by four. A 0.5Ω ESR for C1 will have the same effect as a 2Ω increase in CAT661 output impedance.

Output voltage ripple is determined by the value of C2 and the load current. C2 is charged and discharged at a current roughly equal to the load current. The internal switching frequency is one-half the oscillator frequency.

VRIPPLE = IOUT/(FOSC x C2) + IOUT x ESRC2

For example, with a 25kHz oscillator frequency (12.5kHz switching frequency), a 150 μ F C2 capacitor with an ESR of 0.2 Ω and a 100mA load peak-to-peak the ripple voltage is 45mV.

VRIPPLE vs. FOSC

VRIPPLE (mV)	IOUT (mA)	FOSC (kHz)	C2 (μF)	C2 ESR (Ω)
45	100	25	150	0.2
25	100	135	150	0.2

Figure 6. Oscillator

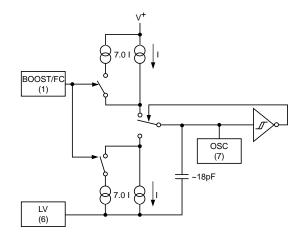
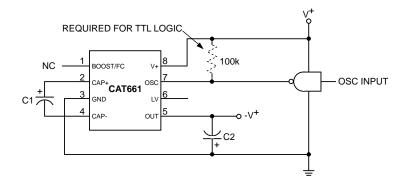


Figure 7. External Clocking



CAPACITOR SUPPLIERS

The following manufacturers supply low-ESR capacitors:

Manufacturer	Capacitor Type	Phone	WEB	Email	Comments
AVX/Kyocera	TPS/TPS3	843-448-9411	www.avxcorp.com	avx@avxcorp.com	Tantalum
Vishay/Sprague	595	402-563-6866	www.vishay.com		Aluminum
Sanyo	MV-AX, UGX	619-661-6835	www.sanyo.com	Svcsales@sanyo.com	Aluminum
Nichicon	F55	847-843-7500	www.nichicon-us.com	_	Tantalum
	HC/HD				Aluminum

Capacitor manufacturers continually introduce new series and offer different package styles. It is recommended

that before a design is finalized capacitor manufacturers should be surveyed for their latest product offerings.

CONTROLLING LOSS IN CAT661 APPLICATIONS

There are three primary sources of voltage loss:

1. Output resistance

VLOSS = ILOAD x ROUT, where ROUT is the CAT661 output resistance and ILOAD is the load current.

Charge pump (C1) capacitor ESR:

VLOSSC1 \approx 4 x ESRC1 x ILOAD, where ESRC1 is the ESR of capacitor C1.

3. Output or reservoir (C2) capacitor ESR:

 $VLOSSC2 = ESRC2 \times ILOAD$, where ESRC2 is the ESR of capacitor C2.

Increasing the value of C2 and/or decreasing its ESR will reduce noise and ripple.

The effective output impedance of a CAT661 circuit is approximately:

Rcircuit ≈ Rout 661 + (4 x ESRC1) + ESRC2

VOLTAGE INVERSION POSITIVE-TO-NEGATIVE

The CAT661 easily provides a negative supply voltage from a positive supply in the system. Figure 8 shows a typical circuit. The LV pin may be left floating for positive input voltages at or above 3.3V.

TYPICAL APPLICATIONS

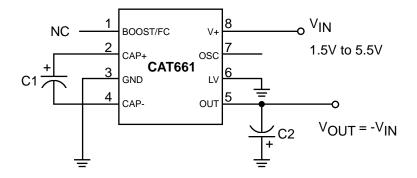


Figure 8: Voltage Inverter

POSITIVE VOLTAGE DOUBLER

The voltage doubler circuit shown in figure 9 gives VOUT = 2 x VIN for input voltages from 2.5V to 5.5V.

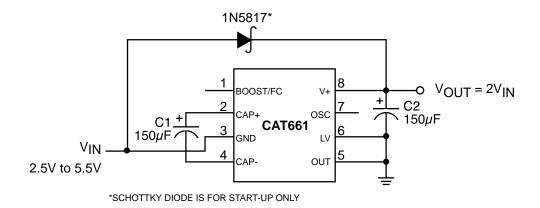


Figure 9: Voltage Doubler

PRECISION VOLTAGE DIVIDER

A precision voltage divider is shown in figure 10. With load currents under 100nA, the voltage at pin 2 will be within 0.002% of V+/2.

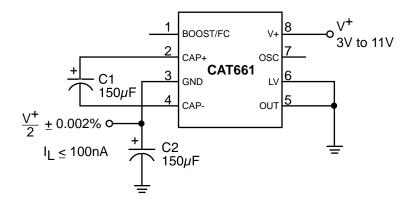


Figure 10: Precision Voltage Divider (Load ≤ 100nA)

11

BATTERY VOLTAGE SPLITTER

Positive and negative voltages that track each other can be obtained from a battery. Figure 11 shows how a 9V battery can provide symmetrical positive and negative voltages equal to one-half the battery voltage.

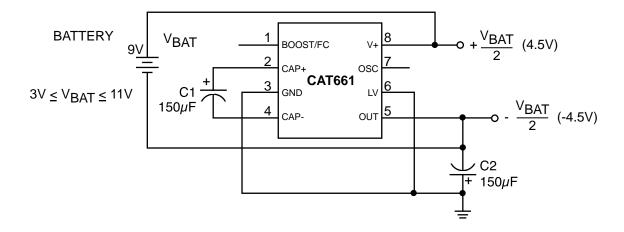


Figure 11: Battery Splitter

CASCADE OPERATION FOR HIGHER NEGATIVE VOLTAGES

The CAT661 can be cascaded as shown in figure 12 to generate more negative voltage levels. The output resistance is approximately the sum of the individual CAT661 output resistance.

 V_{OUT} = -N x V_{IN} , where N represents the number of cascaded devices.

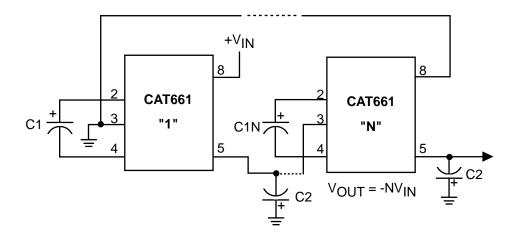


Figure 12: Cascading to Increase Output Voltage

PARALLEL OPERATION

Paralleling CAT661 devices will lower output resistance. As shown in figure 13, each device requires its own pump capacitor, C2, but the output reservoir capacitor is shared with all devices. The value of C2 should be increased by a factor of N, where N is the number of devices.

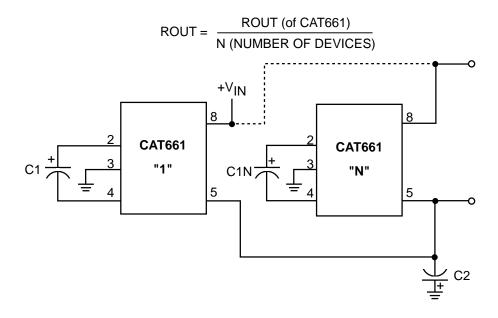
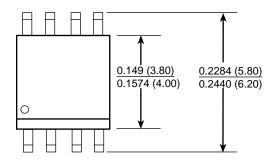
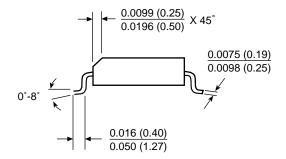
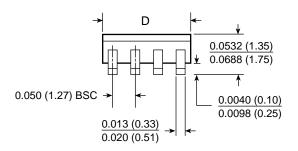


Figure 13: Reduce Output Resistance by Paralleling Devices

PACKAGE MECHANICAL DRAWINGS 8-LEAD 150 WIDE SOIC (S, X)

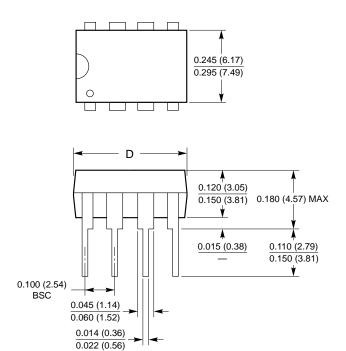


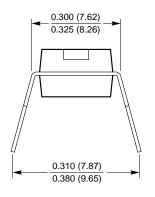




Dimension D		
Pkg	Min	Max
8L	0.1890(4.80)	0.1968(5.00)

8-LEAD 300 MIL WIDE PLASTIC DIP (P)





Dimension D			
Pkg	Min	Max	
8L	0.355 (9.02)	0.400 (10.16)	

Notes:

- 1. Complies with JEDEC Publication 95 MS001 dimensions; however, some of the dimensions may be more stringent.
- 2. All linear dimensions are in inches and parenthetically in millimeters.

8-PAD TDFN (RD8, ZD8) 8 2X 0.15C 0.0 - 0.05 -(1) 4 4.00+0.10 (\bar{S}) PIN 1 **INDEX AREA** //0.10C 0.20 REF. △0.08 C (5) **DAP SIZE 3.5 X 2.4** -0.10 MAX TYP. 3.00±0.10 NOTE: 0.15 1. ALL DIMENSIONS ARE IN mm. 0.10 **-** 0.15 ANGLES IN DEGREES. PIN 1 ID 0.20 2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS. └ 0.20 **COPLANARITY SHALL NOT** 0.10 EXCEED 0.08mm. 3. WARPAGE SHALL NOT └0.50<u>+</u>0.10 (8x) EXCEED 0.10mm. (1)0.30±0.05 (8x) 4. PACKAGE LENGTH/PACKAGE - 0.80 TYP. (6x) WIDTH ARE CONSIDERED AS SPECIAL CHARACTERISTIC. (S) **⊕** 0.10 **(M)** CAB -2.40 REF. (2x)-

REVISION HISTORY

Date	Rev.	Reason
10/15/03	G	Updated Description - eliminated Commercial temperature range
10/27/04	Н	Minor changes throughout data sheet
1/20/2005	I	Changed ordering information for CAT661EXA to CAT661EVA
		Changed ordering information for CAT661EXA-TE13 to CAT661EVA-TE13
04/22/2005	J	Removed Preliminary Information from data sheet header

Copyrights, Trademarks and Patents

© Catalyst Semiconductor, Inc.

Trademarks and registered trademarks of Catalyst Semiconductor include each of the following:

Beyond Memory ™, DPP ™, EZDim ™, LDD ™, MiniPot™ and Quad-Mode™

Catalyst Semiconductor has been issued U.S. and foreign patents and has patent applications pending that protect its products. For a complete list of patents issued to Catalyst Semiconductor contact the Company's corporate office at 408.542.1000.

CATALYST SEMICONDUCTOR MAKES NO WARRANTY, REPRESENTATION OR GUARANTEE, EXPRESS OR IMPLIED, REGARDING THE SUITABILITY OF ITS PRODUCTS FOR ANY PARTICULAR PURPOSE, NOR THAT THE USE OF ITS PRODUCTS WILL NOT INFRINGE ITS INTELLECTUAL PROPERTY RIGHTS OR THE RIGHTS OF THIRD PARTIES WITH RESPECT TO ANY PARTICULAR USE OR APPLICATION AND SPECIFICALLY DISCLAIMS ANY AND ALL LIABILITY ARISING OUT OF ANY SUCH USE OR APPLICATION, INCLUDING BUT NOT LIMITED TO, CONSEQUENTIAL OR INCIDENTAL DAMAGES.

Catalyst Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Catalyst Semiconductor product could create a situation where personal injury or death may occur.

Catalyst Semiconductor reserves the right to make changes to or discontinue any product or service described herein without notice. Products with data sheets labeled "Advance Information" or "Preliminary" and other products described herein may not be in production or offered for sale.

Catalyst Semiconductor advises customers to obtain the current version of the relevant product information before placing orders. Circuit diagrams illustrate typical semiconductor applications and may not be complete.



Catalyst Semiconductor, Inc. Corporate Headquarters 2975 Stender Way Santa Clara, CA 95054 Phone: 408.542.1000

Fax: 408.542.1200 www.catsemi.com Publication #: 5003 Revison: J

Issue date: 04/22/05